

Chemicals contained in products

Package-type

Epson Package name; **PBGA1UE-256 / Mold : Halogen free**

JEITA Package name; **(P-LBGA-0256-1717-1.00)**

Solder ball Type; **Lead(Pb) Free**

Weight; **0.84 [g] *Note1**

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	29.2	Silicon	7440-21-3	29.2	999894	Base material
			Boron	7440-42-8	0.00006	5	Dopant
			Phosphorus	7723-14-0	0.0001	2	Dopant
			Aluminum	7429-90-5	0.0006	2	Metalization
			Arsenic *Note3	7440-38-2	0.0001	5	Dopant
			Fluorine *Note3	7782-41-4	0.00006	20	Dopant
			Titanium *Note3	7440-32-6	0.0006	20	Metalization
			Molybdenum *Note3	7439-98-7	0.0006	20	Metalization
			Tungsten *Note3	7440-33-7	0.0009	30	Metalization
			Cobalt *Note3	7440-48-4	0.00006	2	Metalization
Package	Stress buffer coat	0.58	Polyimide	-	0.58	1000000	Stress buffer coat *Note4
	Substrate	85.48	Glass-cloth	65997-17-3	0.70	200000	Reinforcement
			Epoxy Resin	-	4.41	100000	Base material
			Bismaleimide	13676-54-5	4.18	100000	Base material
			Triazine	25722-66-1	26.42	150000	Base material
			Brominated Flame retardant	-	13.21	26800	Flame retardant
			Copper	7440-50-8	13.21	394200	Copper foil
			Nickel	7440-02-0	19.81	20000	Plating
			Gold	7440-57-5	3.54	9000	Plating
	Die Bonding material	55.90	Epoxy resin	-	52.07	75000	Base material
			Ester resin	-	2.64	475000	Base material
			Silicon dioxide	7631-86-9	1.19	450000	Filler
	Solder ball	110.51	Tin	7440-31-5	105.81	957500	Main constituent
			Silver	7440-22-4	3.87	35000	Main constituent
			Copper	7440-50-8	0.83	7500	Main constituent
	Bonding wire	6.00	Gold	7440-57-5	6.00	1000000	Main constituent
	Mold resin	552.33	Silica	60676-86-0	496.27	898500	Filler
			Epoxy Resin	-	30.38	55000	Main constituent
			Carbon Black	1333-86-4	0.83	1500	Coloring agent
			Phenol Resin	-	24.85	45000	Main constituent

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.